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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

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For: FLEXIBLE BALL GRID ARRAY
CHIP SCALE PACKAGES

Confirmation No.: 5108

Examiner: S. Clark

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of U.S. patents are not being submitted pursuant to M.P.E.P. 609 III A(2). Copies of foreign patent documents and non-patent literature are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an

admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

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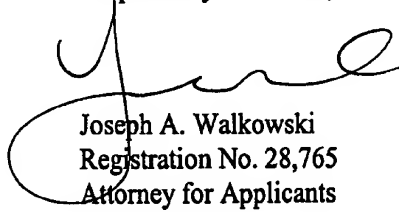
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Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed concurrently with an RCE in the above-identified application, and therefore no additional fee is due.

Respectfully submitted,



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JAW/dlm:ljb

Enclosures: Form PTO-1449 or PTO/SB/08
Copy of non-US documents cited